October 21 (Wed.), 2026

[Oral 08] CMP Consumables (I)

15:10-16:35

International Conference Hall (B1F)

● Session Chair: Xinping Qu (Fudan Univ., China)

15:10-15:35 [Oral 08-1]	**[Invited]** Advanced Ceria Slurries for SiO_2 CMP: Polishing Mechanism of Nanoceria and Emerging Applications Minami Hisataka (Resonac Corp., Japan)
15:35-15:55 [Oral 08-2]	W CMP Oxidants for Ultra-low Chemical Dissolution with High Removal Rate Yearin Byun, Thanh Cuong Nguyen, Inkwon Kim, Heechul Moon, and Sangkyun Kim (Samsung Electronics Co., Ltd., Korea)
15:55-16:15 [Oral 08-3]	Advanced Soft Pad Conditioning Solutions for Improved Pad Life and Defectivity in Cu Barrier Applications Uma Rames Krishna Lagudu, Chikai Chiu, Prasoon Gupta, Jiadi Fan (3M, USA), Holden Lee, Chung I Ho, Jason Lin, Yuhsun Wang (3M, Taiwan), Changwan Bea, Yoonghee Na (3M, Korea), Inki Kim (3M, USA), Benson Chen (3M, Taiwan), and Yongsuk Yang (3M, Korea)
16:15-16:35 [Oral 08-4]	CMP Process and Slurr ies for Memory Device Stacking Yuchun Wang (Anji Microelectronics, China)